



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re: Application of:
Eugene P. Marsh

Serial No.: 10/848,985

Filed: May 18, 2004

For: **SURFACE TREATMENT OF AN OXIDE
LAYER TO ENHANCE ADHESION OF A
RUTHENIUM METAL LAYER**

§
§ Group Art Unit: 2818
§
§ Examiner: H. Jey Tsai
§
§ Atty. Docket: 2002-0717.01/US
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Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Certificate of Mailing (37 CFR §1.8)

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail, postage prepaid, in an envelope addressed to:
Commissioner for Patents, PO Box 1450, Alexandria, VA 22313-1450, on the date below:

May 5, 2006
Date

Kevin D. Perkins
Signature

INFORMATION DISCLOSURE STATEMENT

In compliance with the duty of disclosure under 37 C.F.R. § 1.56, Applicants respectfully request that this Information Disclosure Statement be entered and that the references listed on the attached Form PTO-1449 be considered by the Examiner and made of record. As the references include printed copies of web pages, copies of the references are included herewith.

In accordance with 37 C.F.R. § 1.97(g), this Information Disclosure Statement is not to be construed as a representation that a search has been made or that no other possible material information as defined in 37 C.F.R. § 1.56(a) exists.

The following references are cited for the Examiner's review:

Web Pages

Power Chemical Corp., product information at
www.powerchemical.net/coupling.htm; date unknown, printed April, 2006.

Mitsubishi International Corp., product information at
www.micchem.com/products/SilaneCouplingAgents.htm; date unknown, printed April, 2006.

Semiconfareast, technical information at
www.semiconfareast.com/polysilicon-deposition.htm; date unknown, printed April, 2006.

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As this information is being submitted within three months of the date of filing of the application, Applicant understands that no fee or certification is required for the submission and consideration of this information at this time.

If there are any matters which may be resolved or clarified through telephone interview, the Examiner is respectfully requested to contact Applicant's undersigned attorney at the number indicated.

* * * *

A Form PTO-1449 is enclosed herewith.

Respectfully submitted,


Kevin D. Martin

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Sheet: 1 of: 1

FORM: PTO-1449 (REV: 7-80)	U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE	Atty Docket No: 2002-0717.01/US	Serial No: 10/848,985
INFORMATION DISCLOSURE STATEMENT BY APPLICANT (37 CFR 1.98(b)) <i>(use several sheets if necessary)</i>		Applicant: Eugene P. Marsh, et al.	
		Filing Date: May 18, 2004	Group: 2812

U.S. PATENT DOCUMENTS

Examiner Initial	Document						
	AA						
	AB						
	AC						
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FOREIGN PATENT DOCUMENTS

Examiner Initial	Document Number	Date	Country	Class	Subclass	Translation	
						Yes	No
	AT					<input type="checkbox"/>	<input type="checkbox"/>
	AU					<input type="checkbox"/>	<input type="checkbox"/>

Initial

OTHER REFERENCES (including author, title, date, pertinent pages, etc.)

	AV	Power Chemical Corp., product information at www.powerchemical.net/coupling.htm ; date unknown, printed April, 2006
	AW	Mitsubishi International Corp., product information at www.micchem.com/products/SilaneCouplingAgents.htm ; date unknown, printed April, 2006
	AX	Semiconfareast, technical information at www.semiconfareast.com/polysilicon-deposition.htm ; date unknown, printed April, 2006

Examiner:	Date Considered:
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EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication with applicant.